

FLIP CHIP-IN-LEADFRAME PACKAGE AND PROCESS

ABSTRACT

A method for connecting a chip to a leadframe includes forming bumps on a die by a Au stud-bumping technique, and attaching the chip to the leadframe by thermo-compression of the bumps onto bonding fingers of the leadframe. Also a flip chip-in-leadframe package is made according to the method. The package provides improved electrical performance particularly for devices used in RF applications.

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